

WE CLAIM:

1. An ultra-thin film package, characterized in that polymeric film die carrier (or substrate) or polyimide (PI) die carrier (or substrate) is employed, and the leg position for die bonding is made into a recess shape to lower the thickness after bonding, and polymeric film die carrier (or substrate) or PI die carrier (or substrate) is made into a thin film shape by a fabrication technique (chemical etching or laser fabrication method), and the I/O leg position is made into a recess shape and the die is glued to the polymeric film die carrier (or substrate) or PI die carrier (or substrate) and then changed with a package material. By means of a dicing step, a single package granule containing dies is cut, wherein polymeric film die carrier (or substrate) or PI die carrier (or substrate) and the die are soldered at one end of a wire, the other end is mounted with a metal pad within the leg position which is recessed on the polymeric die film carrier (or substrate) or PI die carrier (or substrate), and the electrode of the metal pad is protruded from the back face of the polymeric film die carrier (or substrate) or PI die carrier (or substrate).
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2. An ultra-thin film package as set forth in Claim 1, wherein a metal plate is provided at the polymeric film die carrier (or substrate) or PI die carrier (or substrate), corresponding to the back face of the die position.
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3. An ultra-thin film package as set forth in Claim 1, wherein the electrical bonding of the die with polymeric film die carrier (or substrate) or PI die carrier (or substrate) is a die bonding method such that the I/O bump of the die and the metal pad on the leg position of the polymeric film die carrier (or substrate) or PI die carrier (or substrate) are bonded.

5 4. An ultra-thin film package as set forth in Claim 3, wherein a metal plate is provided at the polymeric film die carrier (or substrate) or PI die carrier (or substrate), corresponding to the back face of the die position.

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